



Material Content Data Sheet



Sales Product Name		BTS3125EJ		Issued		26. August 2018		
MA#		MA001599594						
Package		PG-TDSO-8-31		Weight*		67.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.851	1.27	1.27	12666	12666
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		141	
	non noble metal	zinc	7440-66-6	0.038	0.06		565	
	non noble metal	iron	7439-89-6	0.760	1.13		11306	
wire	non noble metal	copper	7440-50-8	30.851	45.90	47.10	459071	471083
	non noble metal	copper	7440-50-8	0.203	0.30	0.30	3016	3016
	encapsulation	organic material	carbon black	1333-86-4	0.098	0.15		1462
encapsulation	plastics	epoxy resin	-	3.832	5.70		57015	
	inorganic material	silicondioxide	60676-86-0	28.819	42.88	48.73	428832	487309
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7399	7399
plating	noble metal	silver	7440-22-4	0.825	1.23	1.23	12273	12273
glue	plastics	epoxy resin	-	0.074	0.11		1094	
	noble metal	silver	7440-22-4	0.347	0.52	0.63	5160	6254
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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